## IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

- 1. (Currently amended) A heat sink for assembly with a semiconductor device component, comprising:
- a heat transfer element <u>fabricated as a unitary structure</u>, configured to be secured to the semiconductor device component, and including at least one passageway including an internally confined portion extending along a nonlinear path through the heat transfer element.
- 2. (Previously presented) The heat sink of claim 1, wherein at least a portion of the heat transfer element comprises a plurality of adjacent, mutually adhered regions comprising thermally conductive material.
- 3. (Previously presented) The heat sink of claim 2, wherein the thermally conductive material comprises a metal.
- 4. (Previously presented) The heat sink of claim 3, wherein the metal comprises copper, aluminum, tungsten, or titanium.
- 5. (Previously presented) The heat sink of claim 2, wherein the thermally conductive material comprises a ceramic or a glass.
- 6. (Previously presented) The heat sink of claim 1, wherein the heat transfer element comprises a plurality of particles that are secured to one another.

- 7. (Currently amended) The heat sink of claim 6, wherein adjacent <del>ones of the</del> particles are sintered together.
- 8. (Currently amended) The heat sink of claim 6, wherein adjacent <del>ones of the</del> particles are secured together with a binder.
- 9. (Currently amended) The heat sink of claim 216, wherein at least some of the plurality of superimposed, contiguous, mutually adhered layers comprise sheets of the thermally conductive material.
- 10. (Original) The heat sink of claim 9, wherein adjacent sheets are secured together with an adhesive material.
- 11. (Original) The heat sink of claim 9, wherein adjacent sheets are thermally bonded together.
- 12. (Currently amended) The heat sink of claim 1, wherein the at least one nonlinear passageway is configured to permit airflow therethrough.
- 13. (Previously presented) The heat sink of claim 1, further comprising a heat dissipation element adjacent to the heat transfer element and extending to a location remote from the semiconductor device component.
- 14. (Previously presented) The heat sink of claim 13, wherein at least a portion of the heat dissipation element comprises a plurality of adjacent, mutually adhered regions comprising thermally conductive material.
- 15. (Previously presented) The heat sink of claim 14, wherein the heat dissipation element includes a plurality of fins.

- 16. (Previously presented) The heat sink of claim 2, wherein the plurality of adjacent, mutually adhered regions comprises a plurality of superimposed, contiguous, mutually adhered layers.
- 17. (Previously presented) The heat sink of claim 14, wherein the plurality of adjacent, mutually adhered regions comprises a plurality of superimposed, contiguous, mutually adhered layers.